

AMENDMENTS IN THE TITLE:

SEMICONDUCTOR DEVICE PACKAGE STRUCTURE AND PACKAGING METHOD
CHIP MOUNTED INTERPOSER, SEMICONDUCTOR DEVICE, SEMICONDUCTOR
CHIP INTERPOSER FABRICATION METHOD, BARE CHIP MOUNTED INTERPOSER,
AND INTERPOSER SHEET

AMENDMENTS IN THE SPECIFICATION:

Page 3, Line 25 (Paragraph beginning thereat) through Page 6, Line 1, please replace with the following:

(1) This invention includes: a substrate-like or frame-like base material on which a plurality of semiconductor chips are mounted; and a semiconductor chip mounted interposer configured by mounting a semiconductor bare chip on an interposer in which inside terminals to which terminals of the mounted semiconductor bare chip are connected, outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected, testing terminals to which testing electrodes of a testing apparatus are connected, and conductive wiring that makes an electrical connection between the inside terminals, the outside terminals and the testing terminals, are formed, and detaching the testing terminals after predetermined reliability testing or operation testing,
wherein the semiconductor chip mounted interposer is mounted along with another semiconductor chip to the base material, and the semiconductor chip mounted interposer and the other semiconductor chip are resin sealed along with the base material

(2) In this invention, a semiconductor chip mounted interposer is configured by: mounting a semiconductor bare chip on an interposer in which inside terminals to which terminals of the mounted semiconductor bare chip are connected, outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected, testing terminals to which testing electrodes of a testing apparatus are connected, and conductive wiring that makes an electrical connection between the inside terminals, the outside terminals and the testing terminals, are formed; and detaching the testing terminals after predetermined reliability testing or operation testing.

(3) This invention includes: producing an interposer in which inside terminals to which terminals of the mounted semiconductor bare chip are connected, outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected, testing terminals to which testing electrodes of a testing apparatus are connected, and conductive wiring that makes an electrical connection between the

inside terminals, the outside terminals and the testing terminals, are formed; mounting the semiconductor bare chip on the interposer, and connecting terminals of the semiconductor bare chip to the inside terminals; performing predetermined reliability testing or operation testing by connecting a testing apparatus to the testing terminals; and producing a semiconductor chip mounted interposer by detaching the testing terminals after the predetermined reliability testing or operation testing.

(4) In this invention, in (3), the production of the interposer is performed by joining a plurality of interposers in a single body in the form of a matrix, and the operation testing is performed by consecutively or simultaneously performing the initial reliability testing or operation testing for the plurality of interposers joined in a single body.

(5) In this invention, there are formed: inside terminals to which terminals of a mounted semiconductor bare chip are connected; outside terminals to which terminals other than the terminals of the semiconductor bare chip are connected; testing terminals for connecting testing electrodes of a testing apparatus, formed on the outer side of the inside terminals and the outside terminals, with a larger pitch than the inside terminals and the outside terminals; and conductive wiring that makes an electrical connection between the outside terminals, the inside terminals, and the testing terminals.

(6) This invention is configured by joining a plurality of the interposers of (5) in a single body in the form of a matrix.